

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/25/15120
1.3 Title of PCN	TSHT(China) additional LQFP7x7 32L package assembly line for STM32G03x/G04x listed products
1.4 Product Category	STM32G030x, STM32G031x, STM32G041x
1.5 Issue date	2025-02-04

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	TSHT (China)

### 4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - JSCC (China) Gold wire or copper wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire	Current Wire bonding material: - JSCC (China) Gold wire or copper wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire Added Wire bonding material : - TSHT(China) Copper Palladium wire
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No change - no impact on form, Fit, Function	

### 5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose Microcontroller sub-group decided to extend the capacity through an already qualified back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

### 6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools
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### 7. Timing / schedule

7.1 Date of qualification results	2025-01-30
7.2 Intended start of delivery	2025-01-30
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	15120 MDG-GPAM-RER2501 PCN15120 TSHT(China) add LQ7 32L STM32G03x-4x.Rel Plan.pdf
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<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2025-02-04
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#### **9. Attachments (additional documentations)**

15120 Public product.pdf  
 15120 MDG-GPAM-RER2501 PCN15120 TSHT(China) add LQ7 32L STM32G03x-4x.Rel Plan.pdf  
 15120 \_Additional information.pdf

#### **10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	STM32G030K6T6	
	STM32G030K6T6TR	
	STM32G030K8T6	
	STM32G030K8T6TR	
	STM32G031K6T6	
	STM32G031K8T3	
	STM32G031K8T6	
	STM32G031K8T7	
	STM32G031K8T7TR	
	STM32G041K6T6	
	STM32G041K8T6	

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